2N5302

High-Power NPN Silicon Transistor

High−power NPN silicon transistors are for use in power amplifier and switching circuits applications.

Features
- Low Collector−Emitter Saturation Voltage − $V_{CE(sat)}$ = 0.75 Vdc (Max) @ I_C = 10 Adc
- Pb−Free Package is Available*

MAXIMUM RATINGS (Note 1) (T_J = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Collector−Emitter Voltage	V_{CEO}	60	Vdc
Collector−Base Voltage	V_{CB}	60	Vdc
Collector Current – Continuous (Note 2)	I_C	30	Adc
Base Current	I_B	7.5	Adc
Total Device Dissipation @ T_C = 25°C Derate above 25°C	P_D	200 1.14	W W/°C
Operating and Storage Junction Temperature Range	T_J, T_{stg}	−65 to +200	°C

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction−to−Case	θ_{JC}	0.875	°C/W
Thermal Resistance, Case−to−Ambient	θ_{CA}	34	°C/W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.
1. Indicates JEDEC Registered Data.
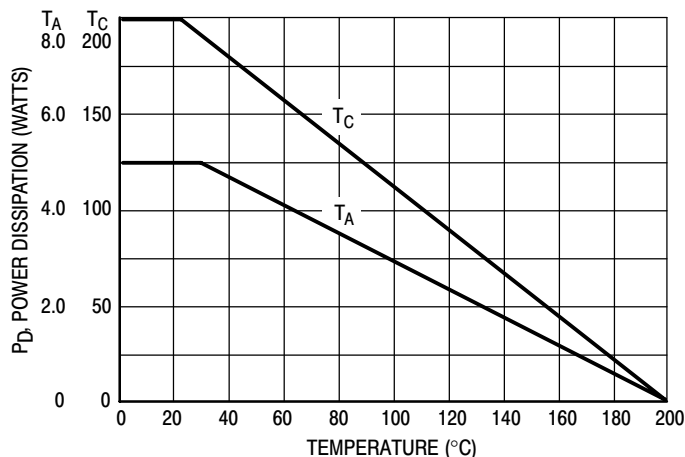2. Pulse Test: Pulse Width = 5 μs, Duty Cycle ≤ 10%.
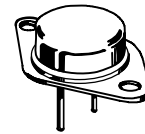

Figure 1. Power Temperature Derating Curve

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

**30 AMPERES
POWER TRANSISTOR
NPN SILICON
60 VOLTS, 200 WATTS**

**TO−204AA (TO−3)
CASE 1−07
STYLE 1**

MARKING DIAGRAM

2N5302G
AYYWW
MEX

2N5302 = Device Code
G = Pb−Free Package
A = Location Code
YY = Year
WW = Work Week
MEX = Country of Origin

ORDERING INFORMATION

Device	Package	Shipping
2N5302	TO−204	100 Units/Tray
2N5302G	TO−204 (Pb−Free)	100 Units/Tray

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS (Note 3)				
Collector–Emitter Sustaining Voltage (Note 4) (I_C = 200 mAdc, I_B = 0)	$V_{CEO(sus)}$	60	–	Vdc
Collector Cutoff Current (V_{CE} = 60 Vdc, I_B = 0)	I_{CEO}	–	5.0	mAdc
Collector Cutoff Current (V_{CE} = 60 Vdc, $V_{EB(off)}$ = 1.5 Vdc)	I_{CEX}	–	1.0	mAdc
Collector Cutoff Current (V_{CE} = 60 Vdc, $V_{EB(off)}$ = 1.5 Vdc, T_C = 150°C)	I_{CEX}	–	10	mAdc
Collector Cutoff Current (V_{CB} = 80 Vdc, I_E = 0)	I_{CBO}	–	1.0	mAdc
Emitter Cutoff Current (V_{BE} = 5.0 Vdc, I_C = 0)	I_{EBO}	–	5.0	mAdc
ON CHARACTERISTICS				
DC Current Gain (Note 4) *(I_C = 1.0 Adc, V_{CE} = 2.0 Vdc) *(I_C = 15 Adc, V_{CE} = 2.0 Vdc) (I_C = 30 Adc, V_{CE} = 4.0 Vdc)	h_{FE}	40 15 5.0	– 60 –	–
*Collector–Emitter Saturation Voltage (Note 4) (I_C = 10 Adc, I_B = 1.0 Adc) (I_C = 20 Adc, I_B = 2.0 Adc)2 (I_C = 30 Adc, I_B = 6.0 Adc)	$V_{CE(sat)}$	– – –	0.75 2.0 3.0	Vdc
*Base Emitter Saturation Voltage (Note 4) (I_C = 10 Adc, I_B = 1.0 Adc) (I_C = 15 Adc, I_B = 1.5 Adc) (I_C = 20 Adc, I_B = 2.0 Adc)	$V_{BE(sat)}$	– – –	1.7 1.8 2.5	Vdc
*Base–Emitter On Voltage (Note 4) (I_C = 15 Adc, V_{CE} = 2.0 Vdc) (I_C = 30 Adc, V_{CE} = 4.0 Vdc)	$V_{BE(on)}$	– –	1.7 3.0	Vdc
DYNAMIC CHARACTERISTICS (Note 3)				
Current–Gain – Bandwidth Product (I_C = 1.0 Adc, V_{CE} = 10 Vdc, f = 1.0 MHz)	f_T	2.0	–	MHz
Small–Signal Current Gain (I_C = 1.0 Adc, V_{CE} = 10 Vdc, f = 1.0 kHz)	h_{fe}	40	–	–

SWITCHING CHARACTERISTICS (Note 3)

Rise Time		t_r	–	1.0	μs
Storage Time	(V_{CC} = 30 Vdc, I_C = 10 Adc, I_{B1} = I_{B2} = 1.0 Adc)	t_s	–	2.0	μs
Fall Time		t_f	–	1.0	μs

3. Indicates JEDEC Registered Data.
4. Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.

SWITCHING TIME EQUIVALENT TEST CIRCUITS
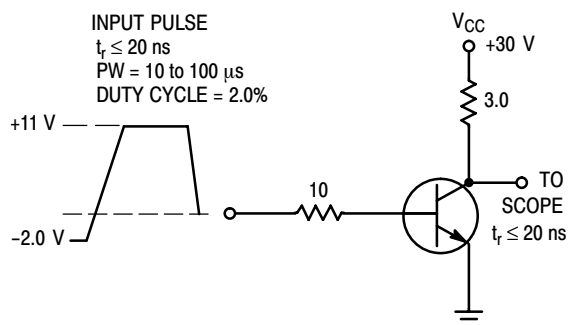
Figure 2. Turn–On time
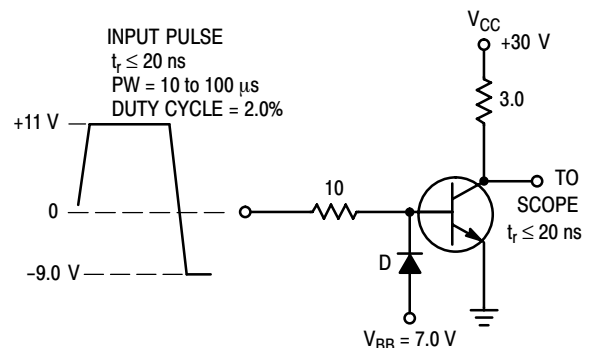
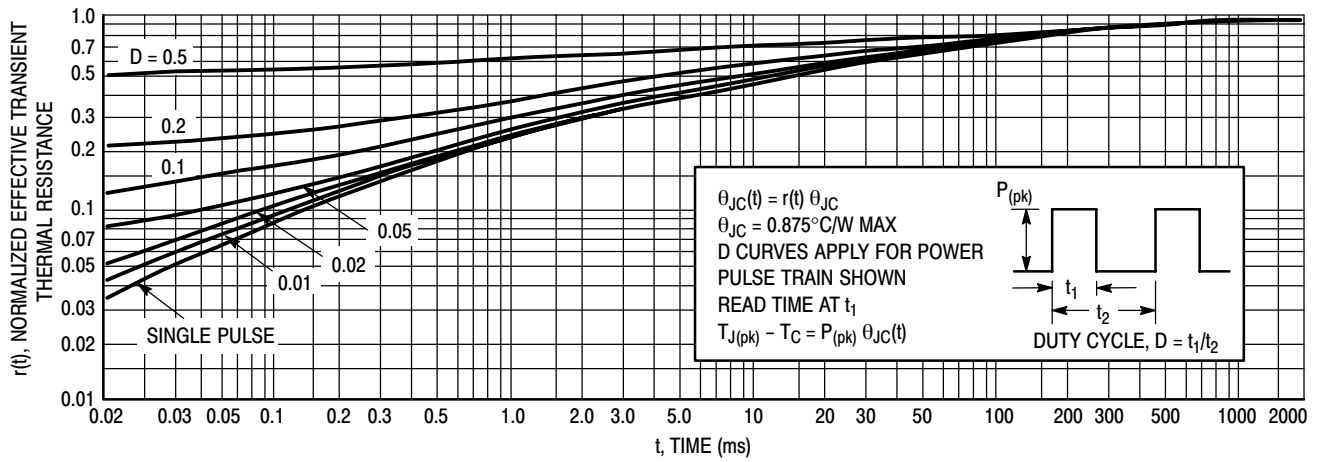Figure 3. Turn–Off time

2N5302
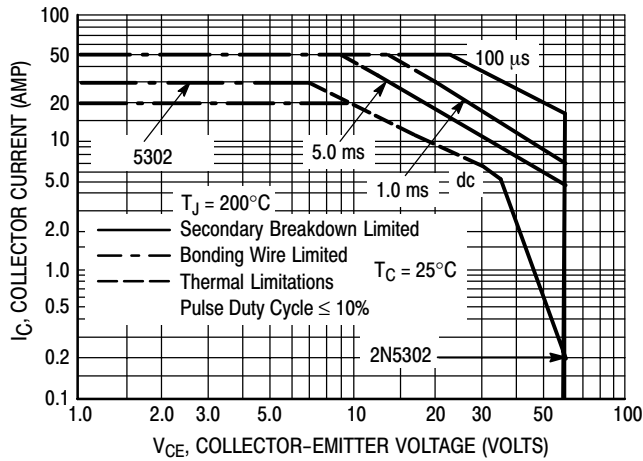

Figure 4. Thermal Response

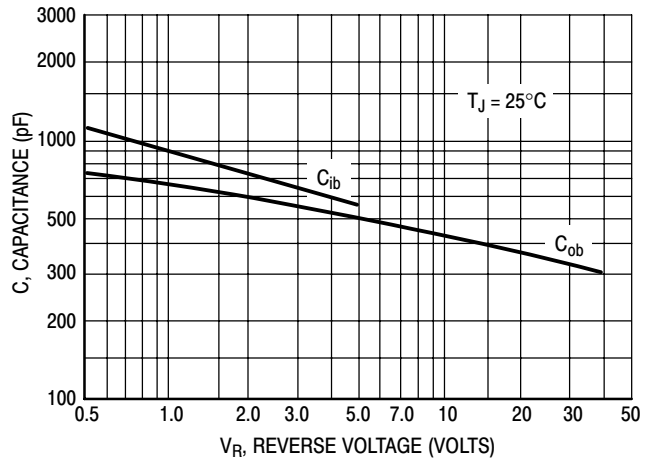

Figure 5. Active–Region Safe Operating Area
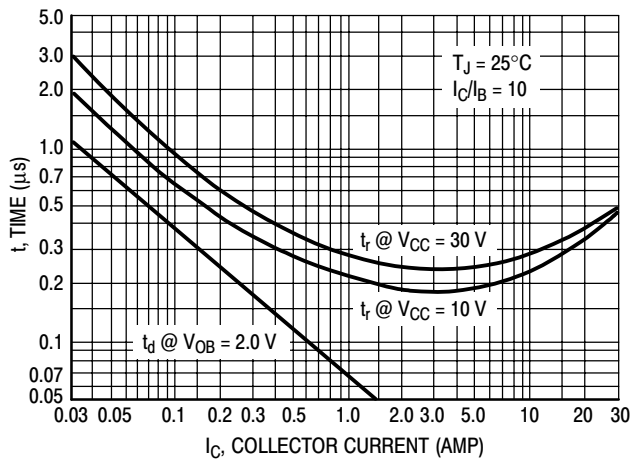

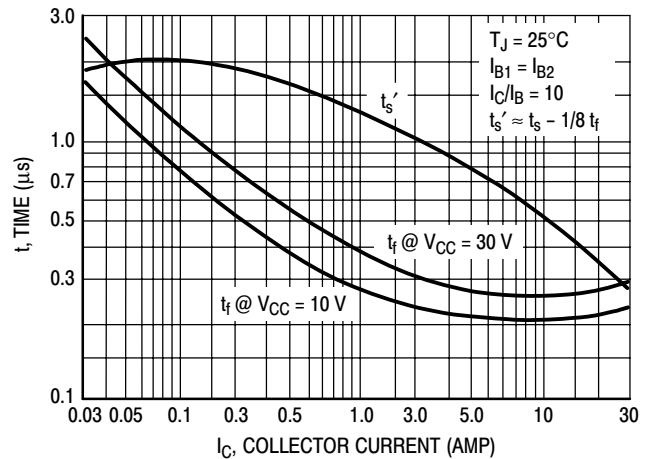**Figure 6. Capacitance versus Voltage**

Figure 7. Turn–On Time
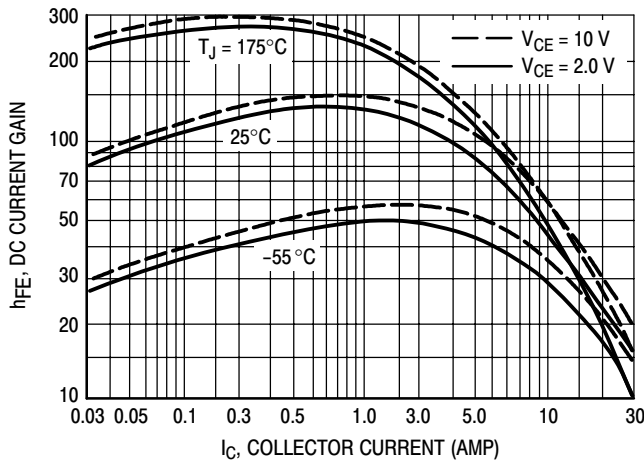

Figure 8. Turn–Off Time
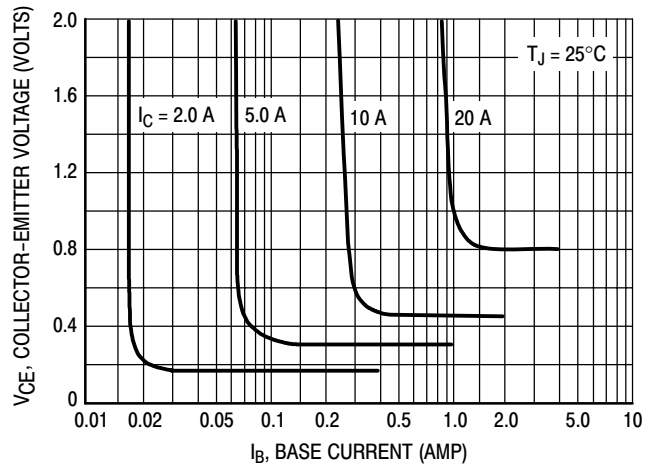
Figure 9. DC Current Gain

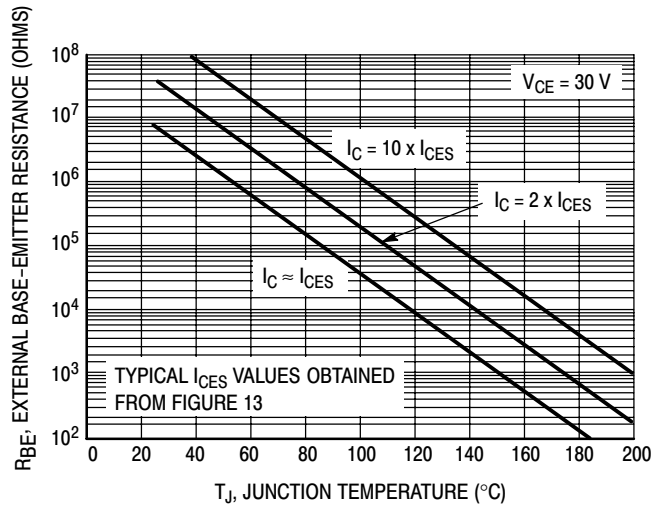**Figure 10. Collector Saturation Region**

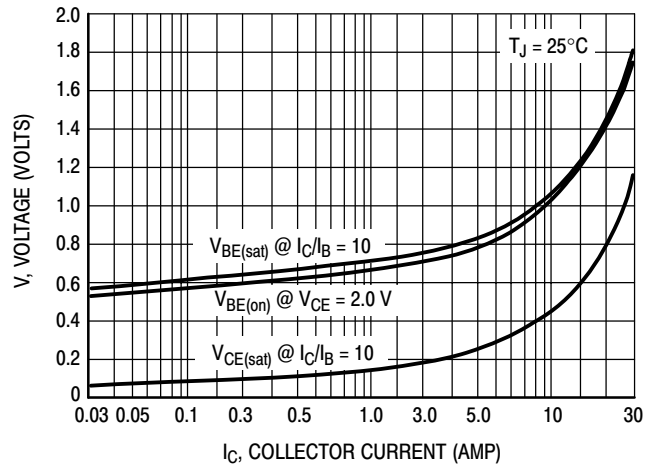
Figure 11. Effects of Base–Emitter Resistance
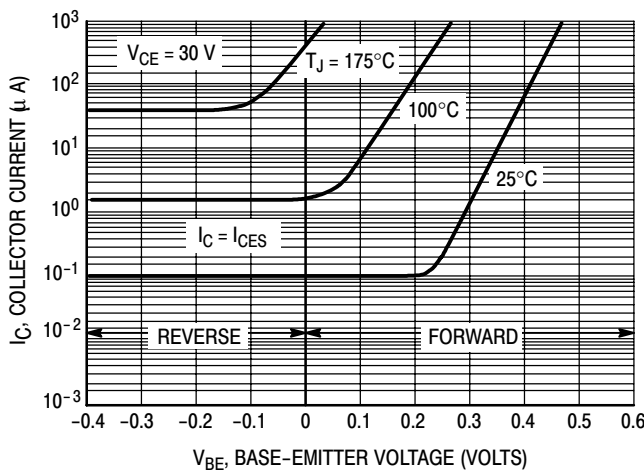

Figure 12. "On" Voltages
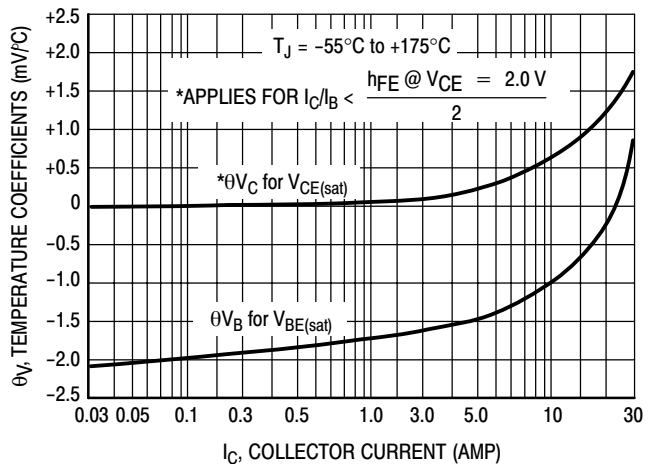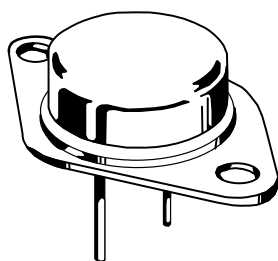

Figure 13. Collector Cut–Off Region

Figure 14. Temperature Coefficients

TO–204 (TO–3)
CASE 1–07
ISSUE Z

DATE 05/18/1988

SCALE 1:1
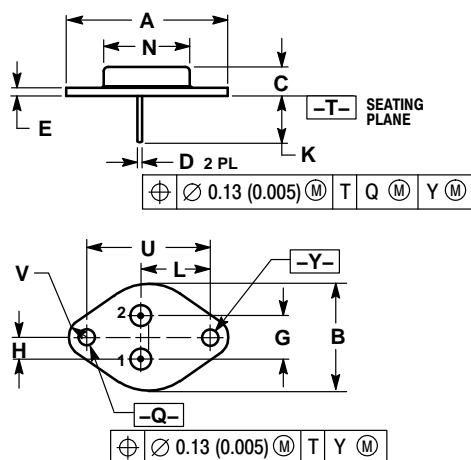
NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. ALL RULES AND NOTES ASSOCIATED WITH REFERENCED TO–204AA OUTLINE SHALL APPLY.

DIM	INCHES MIN	INCHES MAX	MILLIMETERS MIN	MILLIMETERS MAX
A	1.550 REF		39.37 REF	
B	---	1.050	---	26.67
C	0.250	0.335	6.35	8.51
D	0.038	0.043	0.97	1.09
E	0.055	0.070	1.40	1.77
G	0.430 BSC		10.92 BSC	
H	0.215 BSC		5.46 BSC	
K	0.440	0.480	11.18	12.19
L	0.665 BSC		16.89 BSC	
N	---	0.830	---	21.08
Q	0.151	0.165	3.84	4.19
U	1.187 BSC		30.15 BSC	
V	0.131	0.188	3.33	4.77

STYLE 1:
PIN 1. BASE
2. EMITTER
CASE: COLLECTOR

STYLE 2:
PIN 1. BASE
2. COLLECTOR
CASE: EMITTER

STYLE 3:
PIN 1. GATE
2. SOURCE
CASE: DRAIN

STYLE 4:
PIN 1. GROUND
2. INPUT
CASE: OUTPUT

STYLE 5:
PIN 1. CATHODE
2. EXTERNAL TRIP/DELAY
CASE: ANODE

STYLE 6:
PIN 1. GATE
2. EMITTER
CASE: COLLECTOR

STYLE 7:
PIN 1. ANODE
2. OPEN
CASE: CATHODE

STYLE 8:
PIN 1. CATHODE #1
2. CATHODE #2
CASE: ANODE

STYLE 9:
PIN 1. ANODE #1
2. ANODE #2
CASE: CATHODE

ADDITIONAL INFORMATION

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